

PCN: V18-001-F48070-MA

Product Change Notice

Issue Date: 15 March 2018

Change Type:

Major

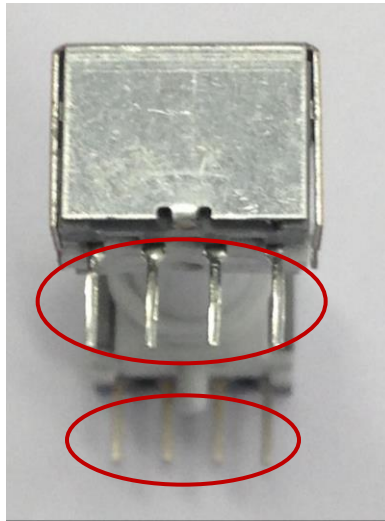
Parts Affected:

| |
|----------------|
| Modules |
| HFBR-3810Z |
| HFBR-3810MSZ |

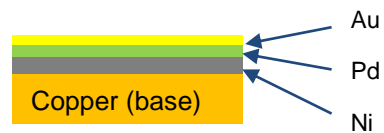
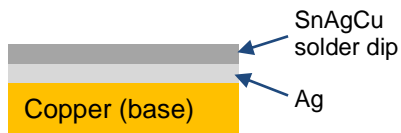
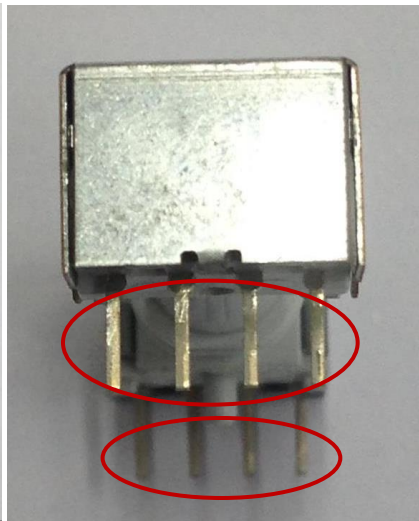
Description and Extent of Change:

Qualify NiPdAu pre-plated lead-frame to adopt industry standard, improve product reliability, product cycle time and to simplify lead-frame supply chain.

Current



New



Active pins (pin1 to pin8 in red circle): Affected by changing to new NiPdAu lead-frame finish.

Metal shield option ground pins (9,10,11): No Change.

Reason for Change:

Eliminate additional solder dip process by implementing NiPdAu Pre-plated lead-frame to improve product reliability, product cycle time and to simplify lead-frame supply chain. The NiPdAu pre-plated lead-frame has been qualified and used in other Broadcom industrial products since year 2015. Lead frame layout and base material remain unchanged.

Effect of Change on Fit, Form, Function, Quality, or Reliability:

The product datasheet specification remains the same. Reliability qualifications have been performed to ensure product reliability.

Effective Date of Change:

Above mentioned change will be effective on or after 6th August 2018 (WW1832). Timing of shipment, on or after 6th August 2018 will vary by part number depending on customer demand, and inventory levels.

Qualification Data:

Available.

These changes have been reviewed and approved by Broadcom Limited engineers and managers per Broadcom Limited procedure: Change Control and Customer Notification, 5962-6052-80.

Please contact your Broadcom Limited field sales for any questions or support requirements. Please return any response as soon as possible, but not to exceed 30 days.